

GSM1072KX5F

20V N-Channel Enhancement Mode MOSFET

Product Description

GSM1072KX5F, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent $R_{DS(ON)}$, low gate charge. These devices are particularly suited for low voltage power management, such as smart phone and notebook computer, and low in-line power loss are needed in commercial industrial surface mount applications.

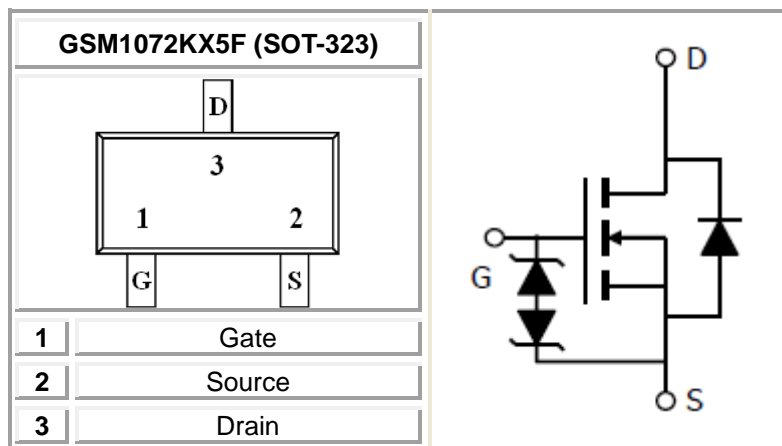
Features

- 20V, 1A, $R_{DS(ON)}=450m\Omega@V_{GS}=4.5V$
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation
- ESD Protected
- SOT-323 package design

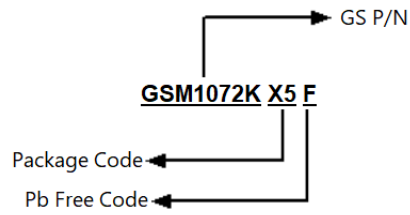
Applications

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Smart Phones, Pagers

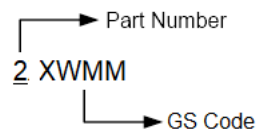
Packages & Pin Assignments



Ordering Information



Marking Information



Part Number	Package	Part Marking
GSM1072KX5F	SOT-323	2XWMM

Absolute Maximum Ratings

($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Typical	Unit
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate –Source Voltage	± 10	V
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	1
		$T_A=70^\circ\text{C}$	0.64
I_{DM}	Pulsed Drain Current	4	A
P_D	Power Dissipation	$T_A=25^\circ\text{C}$	0.29
		$T_A=70^\circ\text{C}$	0.19
T_J	Operating Junction Temperature	-55/150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55/150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient	425	$^\circ\text{C}/\text{W}$

Electrical Characteristics

(T_A=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ	Max.	Unit
Static						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	0.3		1.0	
I _{GSS}	Gate Leakage Current	V _{DS} =0V, V _{GS} =±10V			±10	uA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 16V, V _{GS} =0V			1	uA
		V _{DS} = 16V, V _{GS} =0V, T _J =85°C			30	
R _{DS(on)}	Drain-Source On-Resistance	V _{GS} =4.5V, I _D =0.5A		220	450	mΩ
		V _{GS} =2.5V, I _D =0.4A		280	600	
		V _{GS} =1.8V, I _D =0.2A		390	750	
		V _{GS} =1.5V, I _D =0.1A		540	1200	
V _{SD}	Diode Forward Voltage	I _S =0.5A, V _{GS} =0V			1.3	V
Dynamic						
C _{iss}	Input Capacitance	V _{DS} =16V, V _{GS} =0V f=1MHz		60.7		pF
C _{oss}	Output Capacitance			9.7		
C _{rss}	Reverse Transfer Capacitance			5.4		
Q _g	Total Gate Charge	V _{DS} =10V, V _{GS} =4.5V, I _D ≐0.25A		0.73		nC
Q _{gs}	Gate-Source Charge			0.93		
Q _{gd}	Gate-Drain Charge			0.12		
td(on)	Turn-On Time	V _{DD} =10V, R _L =47Ω, I _D ≐0.2A V _{GEN} =4.5V, R _G =10Ω		5.1		ns
tr				7.4		
td(off)	Turn-Off Time				26.7	
tf				12.3		

Typical Performance Characteristics

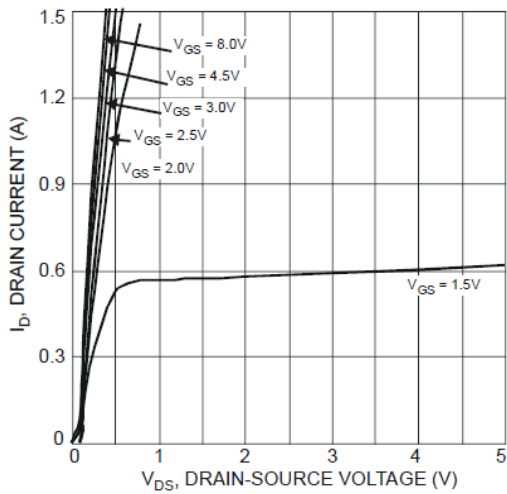


Fig. 1 Typical Output Characteristics

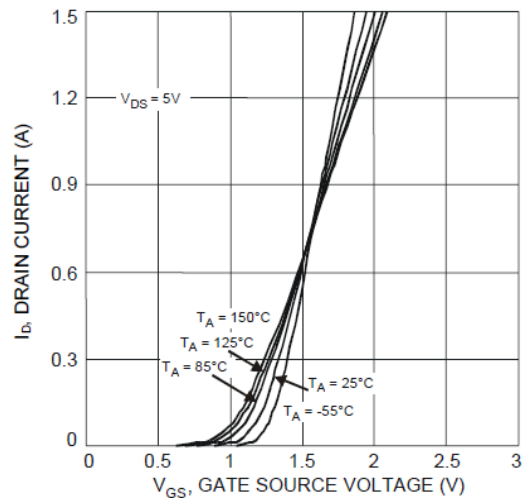


Fig. 2 Typical Transfer Characteristics

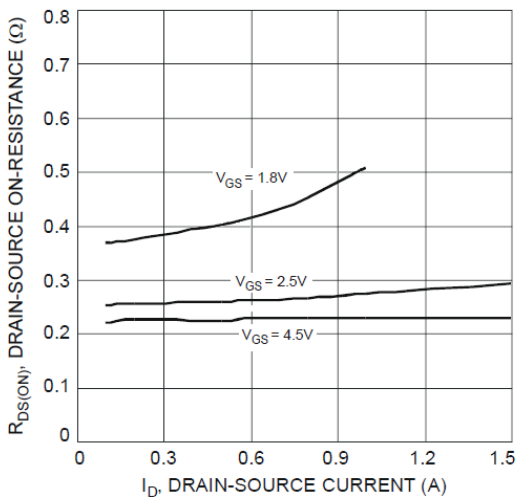


Fig. 3 Typical On-Resistance vs. I_D and V_{GS}

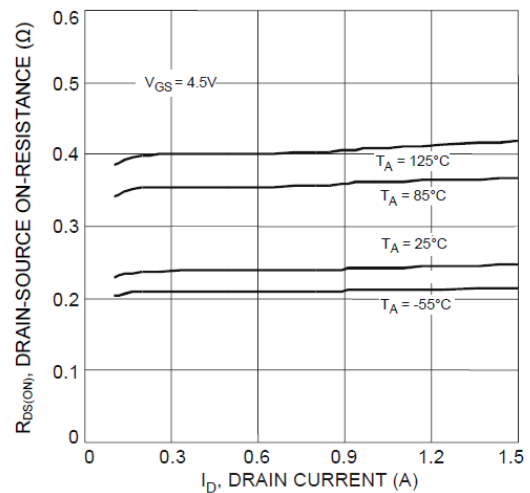


Fig. 4 Typical Drain-Source On-Resistance vs. I_D and T_J

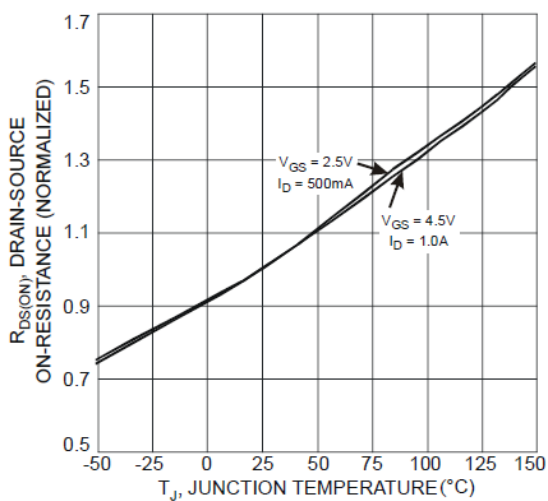


Fig. 5 On-Resistance Variation with T_J

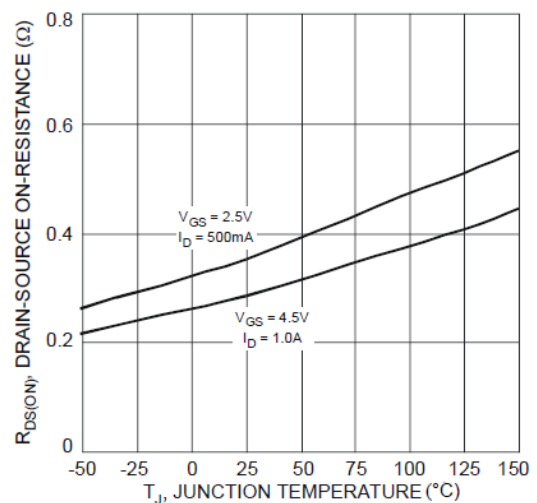


Fig. 6 On-Resistance Variation with T_J

Typical Performance Characteristics (Continue)

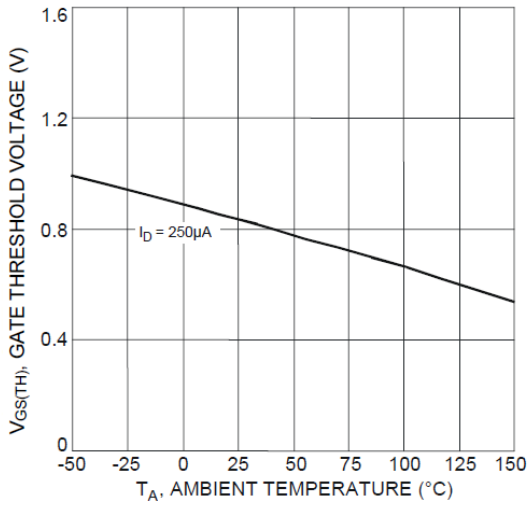


Fig. 7 Gate Threshold Variation vs. T_A

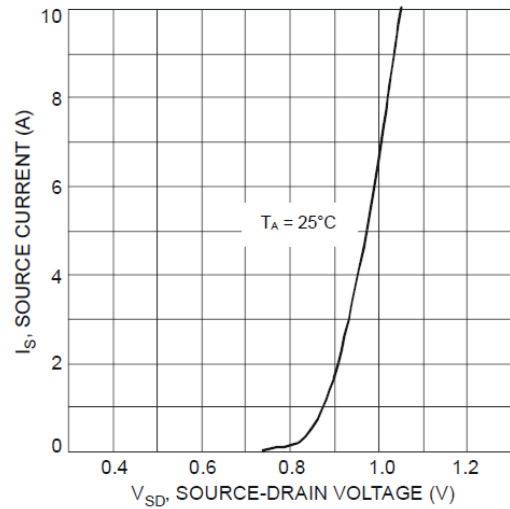


Fig. 8 Diode Forward Voltage vs. Current

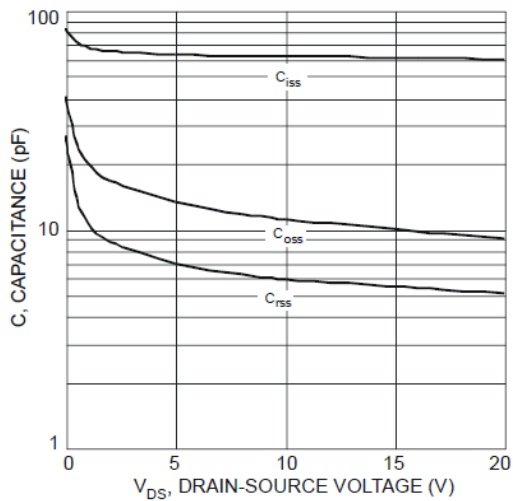


Fig. 9 Typical Capacitance

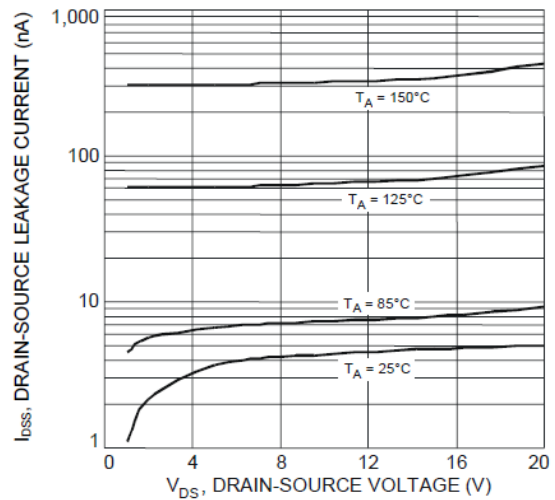


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

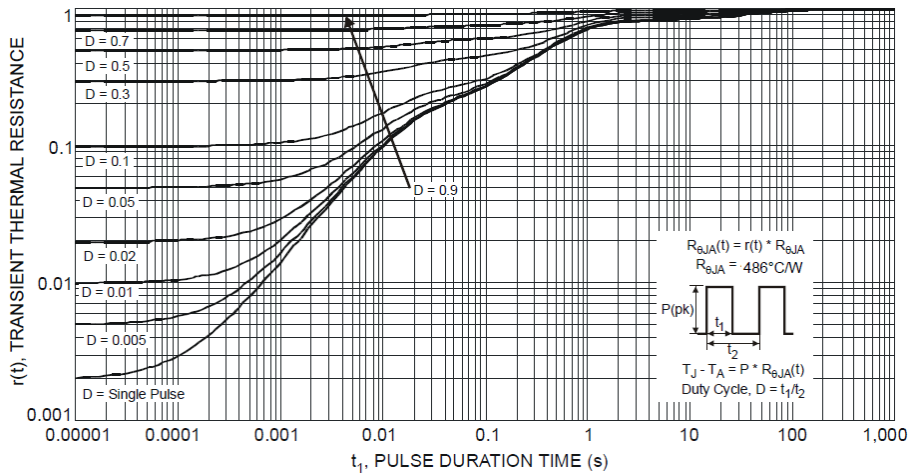








Fig. 11 Transient Thermal Response

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